

REMARKS

The Applicants appreciate the thoroughness with which the subject application has been examined. By this amendment, changes have been made in the drawings, specification and certain claims to overcome the Examiner's objections and rejections and more concisely claim and describe the present invention. New claim 26 has been added. Claims 1-16 and 26 remain in the application for reconsideration by the Examiner. The Examiner's allowance of all pending claims is earnestly solicited.

MATTERS RELATED TO THE RESTRICTION REQUIREMENT

The Applicants acknowledge the finality of the restriction requirement.

MATTERS RELATED TO THE DRAWINGS

In response to the Examiner's objection to the drawings, the Applicants have amended specification paragraph [0016] as suggested by the Examiner. The Applicants also enclose Attachment 1 comprising Figures 4A and 4B revised to indicate that they illustrate prior art.

The Applicants also enclose a revised Figure 11, wherein the cross hatching in the region to the left of the reference character 166 lead line has been corrected to a cross hatching style with a downward slant to the left, consistent with the cross hatching in this region as illustrated in Figures 7-10 as originally submitted. In Figure 11 as originally submitted the cross hatching in this region had a downward slant to the right.

MATTERS RELATED TO THE SPECIFICATION

The Applicants have identified two typographical informalities in the specification and propose to correct these informalities as indicated above in the marked-up specification paragraphs.

MATTERS RELATED TO THE CLAIMS

Claims 1-16 have been rejected under Section 102(a) as anticipated by Applicant's Admitted Prior Art (APA). In the rejection, the Examiner refers specifically to Figure 5 as set forth in the application.

The Applicants note that in prior art Figure 5 the bond pad 156 is disposed in an interconnect level above the power bus 146, where the power bus 146 is disposed in the level 6 interconnect. See paragraph [0031]. In Figure 11, representing a structure according to the Applicant's invention, the aluminum pad 170 is disposed within the same interconnect level as a portion of the power bus, including the conductive via 172, and the power bus 174 extends above the aluminum pad 170.

To further define the invention over the art of record, the preamble of claim 1 has been revised to refer to, "the uppermost bond pad level." Amended claim 1 further now includes, "an interconnect configured to transfer power from one or more of the plurality of contact pads to one or more of the underlying levels of interconnect, wherein at least a portion of the interconnect configured to transfer power is disposed laterally adjacent one or more of the plurality of contact pads." Support for this amendment is found in Figure 11 and the corresponding specification text paragraphs [0040] – [0042].

As can be seen from the Applicant's Figure 5 (the APA referred to by the Examiner), the power bus 146 is disposed in the level 6 interconnect structure and the contact pad 156 is disposed overlying the level 6 power bus 146. The APA does not disclose, "an interconnect configured to transfer power from one or more of the plurality of contact pads to one or more of the underlying levels of interconnect, wherein at least a portion of the interconnect configured to transfer power is disposed laterally adjacent one or more of the plurality of contact pads." Thus it is respectfully suggested that claim 1 as amended is patentably distinct from the APA.

Rejected claims 2 - 11 depend directly or indirectly from amended claim 1. The Applicants respectfully submit that these claims are allowable as they include one or more elements that further distinguish the art of record.

Claim 10 has been amended as set forth above to further distinguish the invention from the art of record.

To patentably distinguish independent claim 12 from the APA, the Applicants have amended the last paragraph of the claim to, "an interconnect structure configured to connect one or more of the underlying levels of interconnect to another of the one or more underlying levels of interconnect, wherein at least a portion of the interconnect structure configured to connect one or more of the underlying levels is disposed laterally adjacent one or more of the plurality of contact pads."

As can be seen from Figure 5, the illustrated structure does not disclose, "an interconnect structure configured to connect one or more of the underlying levels of interconnect to another of the one or more underlying levels of interconnect, wherein at least a portion of the interconnect structure configured to connect one or more of the underlying levels is disposed laterally adjacent one or more of the plurality of contact pads."

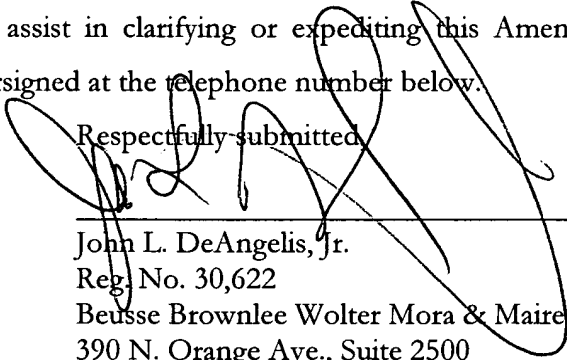
Rejected claims 13 - 16 depend directly or indirectly from independent amended claim 12. The Applicants respectfully submit that these claims are allowable as they include one or more elements that further distinguish the art of record.

New claim 26, depending from claim 1, has been added. This claim claims, "at least a portion of the interconnect configured to transfer power is disposed above one or more of the plurality of contact pads." Support for this claim can be found in Figure 11. Clearly this claim is distinguishable from the prior art of Figure 5.

The Applicants have attempted to comply with all of the points raised in the Office Action and it is believed that the remaining claims in the application, i.e., 1 - 16 and 26 are now in condition for allowance. In view of the foregoing amendments and discussion, it is requested that the Examiner's claim rejections and objections have been overcome. It is respectfully requested that the Examiner reconsider these rejections and objections and issue a Notice of Allowance for all the claims pending in the application.

If a telephone conference will assist in clarifying or expediting this Amendment, the Examiner is invited to contact the undersigned at the telephone number below.

Respectfully submitted,



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CERTIFICATE OF MAILING

I HEREBY CERTIFY that the foregoing Amendment (including Attachment 1) is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 4th day of May, 2005.



Pamela A. Pagel

ATTACHMENT 1

REPLACEMENT SHEETS FOR FIGURES 4A, 4B AND 11